Two 1-Bit, 10MHz, 2nd-Order Delta-Sigma Modulators

Check for Samples: ADS1209

FEATURES

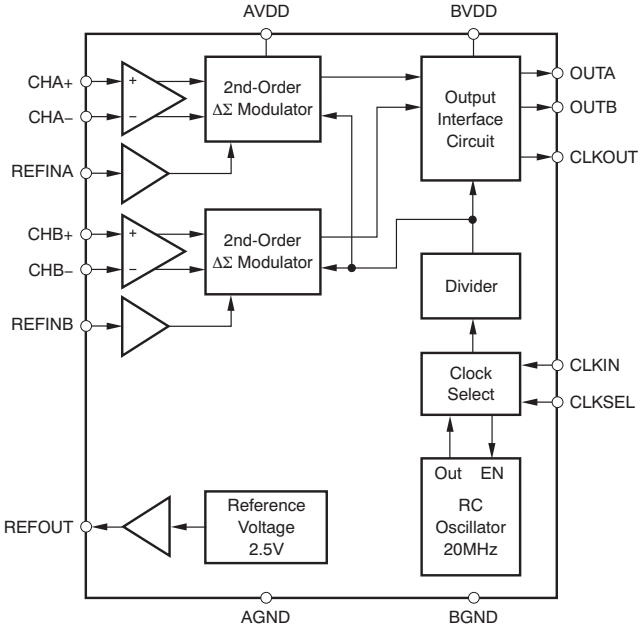
- **16-Bit Resolution**
- **13-Bit Linearity**
- **±2.3V Specified Input Voltage Range**
- **Internal Reference Voltage: 2%**
- **Gain Error: 0.5%**
- **Two Independent Delta-Sigma Modulators**
- **Two Input Reference Buffers**
- **On-Chip Oscillator**
- **Selectable Internal or External Clock**
- **Specified Temperature Range: –40°C to +105°C**
- **TSSOP-24 Package**

APPLICATIONS

- **Motor Control**
- **Current Measurement**
- **Resolver**
- **Industrial Process Control**
- **Instrumentation**

DESCRIPTION

The ADS1209 is a two-channel, high-performance, delta-sigma (ΔΣ) modulator with an 86dB dynamic range, operating from a single +5V supply. The differential inputs are ideal for direct connection to signal sources in an industrial environment. With the appropriate digital filter and modulator rate, the device can be used to achieve 16-bit analog-to-digital (A/D) conversion with no missing codes. Effective accuracy of 14 bits can be obtained with a digital filter bandwidth of 20kHz at a modulator rate of 10MHz. The ADS1209 is designed for use in high-resolution measurement applications including current measurements, industrial process control, and resolvers. It is available in a TSSOP-24 package and is specified for operation over the ambient temperature range of –40°C to +105°C.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
ADS1209	TSSOP-24	PW	–40°C to +105°C	ADS1209SPW	Tube, 60
				ADS1209SPWR	Tape and Reel, 2000

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1)

Over operating ambient temperature range, unless otherwise noted.

		ADS1209	UNIT
Supply voltage, AVDD to AGND		–0.3 to 6	V
Supply voltage, BVDD to BGND		–0.3 to 6	V
Analog input voltage		AGND – 0.3 to AVDD + 0.3	V
Reference input voltage		AGND – 0.3 to AVDD + 0.3	V
Digital input voltage		BGND – 0.3 to BVDD + 0.3	V
Ground voltage difference, AGND to BGND		±0.3	V
Input current to any pin except supply		±10	mA
Operating virtual junction temperature range, T_J		–40 to +150	°C
Operating ambient temperature range, T_{OA}		–40 to +125	°C
ESD ratings, all pins	Human body model (HBM) JEDEC standard 22, test method A114-C.01	+2000	V
	Charged device model (CDM) JEDEC standard 22, test method C101	+500	V

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS

PACKAGE	$T_A \le +25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = +25°C$(1)	$T_A = +70°C$ POWER RATING	$T_A = +85°C$ POWER RATING	$T_A = +105°C$ POWER RATING
TSSOP-24	1420mW	11.3mW/°C	909mW	738mW	511mW

(1) This is the inverse of the traditional junction-to-ambient thermal resistance ($R_{\theta JA}$). Thermal resistances are not production tested and are for informational purposes only.

THERMAL CHARACTERISTICS: TSSOP-24

Over the operating ambient temperature range of –40°C to +105°C, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$R_{\theta JA}$	Junction-to-air thermal resistance	High-K thermal resistance(1)		88		°C/W
$R_{\theta JC}$	Junction-to-case thermal resistance			26		°C/W
P_D	Device power dissipation	CLKSEL = 0, 5V supply			100	mW

(1) Modeled in accordance with the High-K thermal definitions of EIA/JESD51-3.

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RECOMMENDED OPERATING CONDITIONS

PARAMETER		MIN	NOM	MAX	UNIT
Supply voltage, AVDD to AGND		4.5	5	5.5	V
Supply voltage, BVDD to BGND	Low-voltage levels	2.7	3.0	3.6	V
	5V logic levels	4.5	5	5.5	V
Reference input voltage, V_{REF}		0.5	2.5	2.6	V
Operating common-mode signal		0		AVDD	V
Analog inputs	+IN – (–IN)	–0.92 × V_{REF}		+0.92 × V_{REF}	V
External clock(1)		16	20	24	MHz
Operating ambient temperature range, T_{OA}		–40		+125	°C
Specified ambient temperature range, T_A		–40		+105	°C

(1) With reduced accuracy, clock can go from 1MHz up to 33MHz; see Typical Characteristic curves.

ELECTRICAL CHARACTERISTICS

Over operating ambient temperature range of –40°C to +105°C, AVDD = 5V, BVDD = 3V, CHx+ = 0.2V to 4.8V, CHx– = 2.5V, $V_{REFIN} = V_{REFOUT}$ = 2.5V (internal), CLKIN = 20MHz, and 16-bit Sinc^3 filter with OSR = 256, unless otherwise noted.

PARAMETER		TEST CONDITIONS	ADS1209			UNIT
			MIN	TYP(1)	MAX	
RESOLUTION			16			Bits
DC ACCURACY						
INL	Integral linearity error(2)	V_{IN} = ±2.3V_{PP}	–8	±3.8	+8	LSB
		V_{IN} = ±2.0V_{PP}	–4	±1.8	+4	LSB
	Integral linearity match			1	4	LSB
DNL	Differential nonlinearity		–1		+1	LSB
V_{OS}	Input offset error		–3	±1.5	+3	mV
	Input offset error match			0.2	2	mV
TCV_{OS}	Input offset error thermal drift		–8	1	+8	µV/°C
G_{ERR}	Gain error	Referenced to V_{REFIN}	–0.5	±0.02	+0.5	% FSR
	Gain error match			0.1	0.5	% FSR
TCG_{ERR}	Gain error thermal drift			±1.3		ppm/°C
PSRR	Power-supply rejection ratio	4.5V < AVDD < 5.5V		82		dB
ANALOG INPUTS						
FSR	Full-scale differential input voltage range	(CHx+) – (CHx–); CHx– = 2.5V	–V_{REFIN}		+V_{REFIN}	V
	Specified differential input voltage range	(CHx+) – (CHx–); CHx– = 2.5V	–0.92 × V_{REF}		+0.92 × V_{REF}	V
	Absolute operating input voltage range		0		AV_{DD}	V
C_I	Input capacitance	CHx to AGND		3		pF
I_{IL}	Input leakage current	Clock turned off	–1		1	µA
R_{ID}	Differential input resistance			100		kΩ
C_{ID}	Differential input capacitance			2.5		pF
CMRR	Common-mode rejection ratio	At dc		108		dB
		V_{IN} = ±1.25V_{PP} at 40kHz		117		dB
BW	Bandwidth	Full-scale sine wave, –3dB		50		MHz

(1) All typical values are at T_A = +25°C.
(2) Integral nonlinearity is defined as the maximum deviation of the line through the end points of the specified input range, expressed either as the number of LSBs or as a percent of specified input range (4.6V).

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ELECTRICAL CHARACTERISTICS (continued)

Over operating ambient temperature range of –40°C to +105°C, AVDD = 5V, BVDD = 3V, CHx+ = 0.2V to 4.8V, CHx– = 2.5V, $V_{REFIN} = V_{REFOUT}$ = 2.5V (internal), CLKIN = 20MHz, and 16-bit $Sinc^3$ filter with OSR = 256, unless otherwise noted.

PARAMETER		TEST CONDITIONS	ADS1209 MIN	ADS1209 TYP(1)	ADS1209 MAX	UNIT
SAMPLING DYNAMICS						
f_{CLK}	Internal clock frequency	CLKSEL = 1, –40°C ≤ T_A ≤ +85°C	8	10	12	MHz
		CLKSEL = 1, –40°C ≤ T_A ≤ +105°C	7.8	10	12	MHz
f_{CLKIN}	External clock frequency	CLKSEL = 0	1	20	24	MHz
AC ACCURACY						
THD	Total harmonic distortion	V_{IN} = ±2.3V_{PP} at 5kHz		–85	–80	dB
SFDR	Spurious-free dynamic range	V_{IN} = ±2.3V_{PP} at 5kHz	82	86		dB
SNR	Signal-to-noise ratio	V_{IN} = ±2.3V_{PP} at 5kHz	86	90		dB
		V_{IN} = ±2.0V_{PP} at 5kHz	85	89		dB
SINAD	Signal-to-noise + distortion	V_{IN} = ±2.3V_{PP} at 5kHz	80	84		dB
	Channel-to-channel isolation	V_{IN} = ±2.3V_{PP} at 5kHz		100		dB
REFERENCE VOLTAGE OUTPUT						
V_{REFOUT}	Reference output voltage		2.450	2.5	2.550	V
TCV_{REFOUT}	Reference output voltage drift			±20		ppm/°C
	Output voltage noise	f = 0.1Hz to 10Hz, C_L = 10µF		10		$µV_{RMS}$
		f = 10Hz to 10kHz, C_L = 10µF		12		$µV_{RMS}$
I_{REFOUT}	Output current			10		µA
I_{REFSC}	Short-circuit current			0.5		mA
	Turn-on settling time	To accuracy level of 0.1%, no load		100		µs
REFERENCE VOLTAGE INPUT						
V_{REFIN}	Input voltage		0.5	2.5	2.6	V
R_{REFIN}	Input resistance			100		MΩ
C_{REFIN}	Input capacitance			5		pF
I_{REFIN}	Input current				1	µA
DIGITAL INPUTS						
	Logic family		CMOS with Schmitt Trigger			
V_{IH}	High-level input voltage		0.7 × BVDD		BVDD + 0.3	V
V_{IL}	Low-level input voltage		–0.3		0.3 × BVDD	V
I_{IN}	Input current	V_{IN} = BVDD or BGND			±50	nA
C_I	Input capacitance			5		pF
DIGITAL OUTPUTS						
	Logic family			CMOS		
V_{OH}	High-level output voltage	BVDD = 4.5V, I_{OH} = –100µA	4.44			V
V_{OL}	Low-level output voltage	BVDD = 4.5V, I_{OL} = +100µA			0.5	V
C_O	Output capacitance			5		pF
C_L	Load capacitance				30	pF
	Data format			Bit stream		

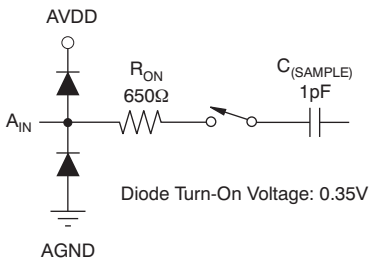
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ELECTRICAL CHARACTERISTICS (continued)

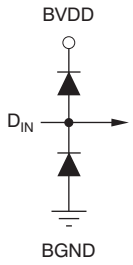
Over operating ambient temperature range of –40°C to +105°C, AVDD = 5V, BVDD = 3V, CHx+ = 0.2V to 4.8V, CHx– = 2.5V, $V_{REFIN} = V_{REFOUT}$ = 2.5V (internal), CLKIN = 20MHz, and 16-bit Sinc^3 filter with OSR = 256, unless otherwise noted.

PARAMETER		TEST CONDITIONS	ADS1209 MIN	ADS1209 TYP(1)	ADS1209 MAX	UNIT
DIGITAL INPUTS						
	Logic family			LVCMOS		
V_{IH}	High-level input voltage	BVDD = 3.6V	2		BVDD + 0.3	V
V_{IL}	Low-level input voltage	BVDD = 2.7V	–0.3		0.8	V
I_{IN}	Input current	V_{IN} = BVDD or BGND			±50	nA
C_I	Input capacitance			5		pF
DIGITAL OUTPUTS						
	Logic family			LVCMOS		
V_{OH}	High-level output voltage	BVDD = 2.7V, I_{OH} = –100µA	BVDD – 0.2			V
V_{OL}	Low-level output voltage	BVDD = 2.7V, I_{OL} = +100µA			0.2	V
C_O	Output capacitance			5		pF
C_L	Load capacitance				30	pF
	Data format			Bit stream		
POWER SUPPLY						
AVDD	Analog supply voltage		4.5	5.0	5.5	V
BVDD	Buffer I/O supply voltage	Low-voltage levels	2.7	3.0	3.6	V
		5V logic levels	4.5	5.0	5.5	V
AIDD	Analog operating supply current	CLKSEL = 1		12.2	17	mA
		CLKSEL = 0		11.8	16	mA
BIDD	Buffer I/O operating supply current	BVDD = 3V, CLKOUT = 10MHz		0.9	2	mA
		BVDD = 5V, CLKOUT = 10MHz		1.3	3	mA
P_D	Power dissipation	CLKSEL = 1, 5V supply		67.5	100.0	mW
		CLKSEL = 0, 5V supply		65.5	95	mW

EQUIVALENT INPUT CIRCUITS



Equivalent Analog Input Circuit

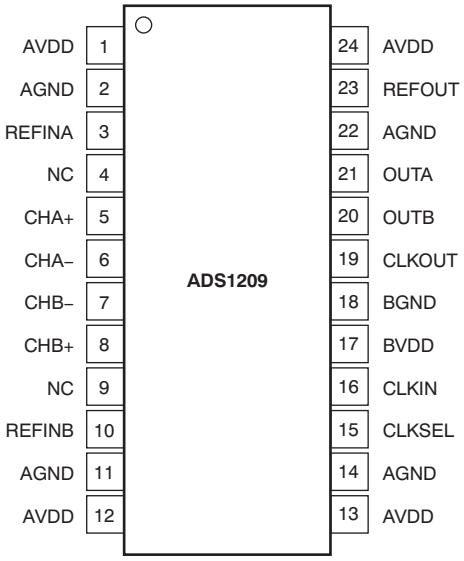


Equivalent Digital Input Circuit

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PIN CONFIGURATION

PW PACKAGE
TSSOP-24
(TOP VIEW)



PIN DESCRIPTIONS

PIN		I/O[1]	DESCRIPTION
NAME	NO.		
AVDD	1	P	Analog power supply; nominal 5V. Decouple to AGND with a 0.1µF ceramic capacitor.
AGND	2	P	Analog ground. Connect to analog ground plane.
REFINA	3	AI	Reference voltage input for channel A
NC	4	NC	This pin is not internally connected
CHA+	5	AI	Fully differential noninverting analog input channel A
CHA–	6	AI	Fully differential inverting analog input channel A
CHB–	7	AI	Fully differential inverting analog input channel B
CHB+	8	AI	Fully differential noninverting analog input channel B
NC	9	NC	This pin is not internally connected
REFINB	10	AI	Reference voltage input for channel B
AGND	11	P	Analog ground. Connect to analog ground plane.
AVDD	12	P	Analog power supply; nominal 5V. Decouple to AGND with a 0.1µF ceramic capacitor.
AVDD	13	P	Analog power supply; nominal 5V. Decouple to AGND with a 0.1µF ceramic capacitor.
AGND	14	P	Analog ground. Connect to analog ground plane.
CLKSEL	15	DI	Clock select input. When this pin is low, an external clock source at CLKIN is used. When high, the internal RC oscillator is used as clock source.
CLKIN	16	DI	External clock input. Must be tied to BVDD or BGND, if not used.
BVDD	17	P	I/O buffer power supply, nominal: 3V. Decouple to BGND with a 0.1µF ceramic capacitor
BGND	18	P	I/O buffer ground. Connect to digital ground plane
CLKOUT	19	DO	Bit stream clock output
OUTB	20	DO	Bit stream data output of channel B modulator
OUTA	21	DO	Bit stream data output of channel A modulator
AGND	22	P	Analog ground. Connect to analog ground plane.
REFOUT	23	AO	Internal reference voltage output, nominal: 2.5V. Decouple to AGND with a 0.1µF ceramic capacitor.
AVDD	24	P	Analog power supply, nominal: 5V. Decouple to AGND with a 0.1µF ceramic capacitor.

(1) AI = analog input; AO = analog output; DI = digital input; DO = digital output; P = power supply; NC = not connected.

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PARAMETER MEASUREMENT INFORMATION

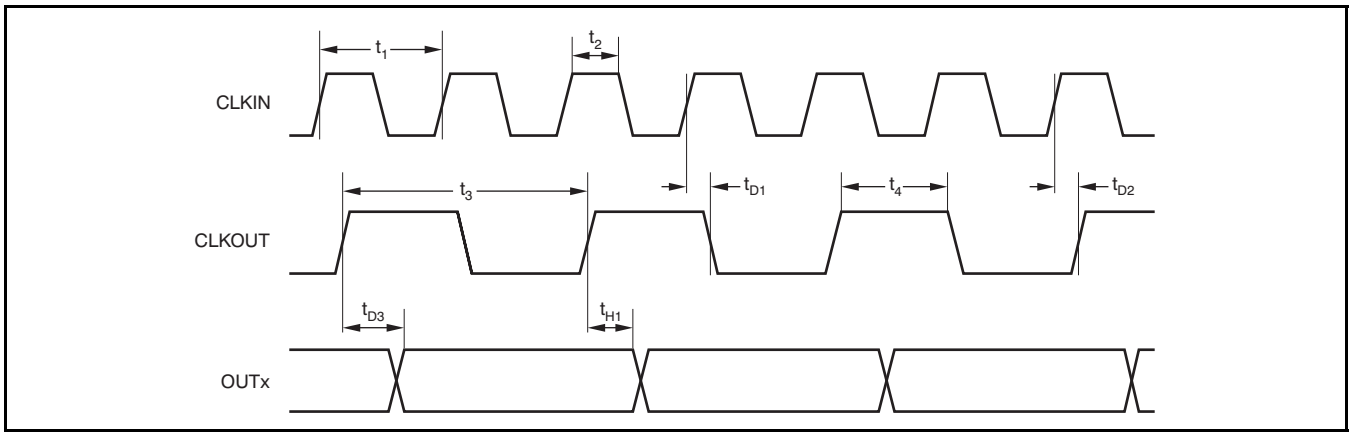


Figure 1. ADS1209 Timing Diagram

TIMING CHARACTERISTICS(1)

Over the recommended operating ambient temperature range of –40°C to +105°C, AV_{DD} = 5V, and BV_{DD} = 2.7V to 5V, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
t_1	CLKIN period	CLKSEL = 0	41.6	1000	ns
t_2	CLKIN high time	CLKSEL = 0	10	t_1 – 10	ns
t_3	CLKOUT period	CLKSEL = 0	2 × t_1		ns
		CLKSEL = 1	83	125	ns
t_4	CLKOUT high time		(t_3/2) – 5	(t_3/2) + 5	ns
t_{D1}	CLKIN rising edge to CLKOUT falling edge delay	CLKSEL = 0		10	ns
t_{D2}	CLKIN rising edge to CLKOUT rising edge delay	CLKSEL = 0		10	ns
t_{D3}	CLKOUT rising edge to new data valid delay	CLKSEL = 0	t_2 + 7		ns
		CLKSEL = 1	(t_3/4) + 8		ns
t_{H1}	Data valid hold time referred to rising CLKOUT edge	CLKSEL = 0	t_2 – 3		ns
		CLKSEL = 1	(t_3/4) – 8		ns

(1) All input signals are specified with t_R = t_F = 1.5ns (10% to 90% of BVDD) and timed from a voltage level of (V_{IL} + V_{IH})/2.

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TYPICAL CHARACTERISTICS

At AVDD = 5V, BVDD = 3V, CHx+ = +0.2V to +4.8V, CHx– = +2.5V, V_{REFIN} = V_{REFOUT} = 2.5V (internal), CLKSEL = 1, and 16-bit Sinc^3 filter, with OSR = 256, unless otherwise noted.

INTEGRAL NONLINEARITY vs INPUT SIGNAL VOLTAGE

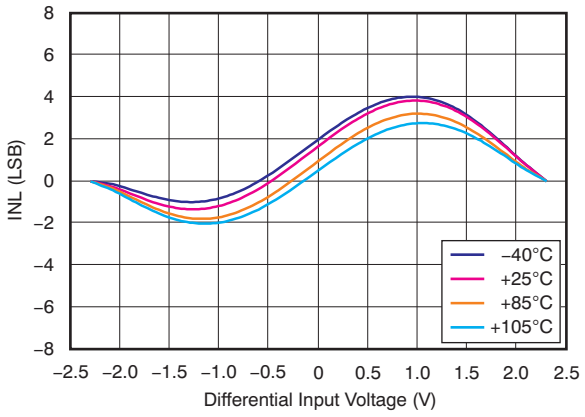


Figure 2.

INTEGRAL NONLINEARITY MATCH vs INPUT SIGNAL

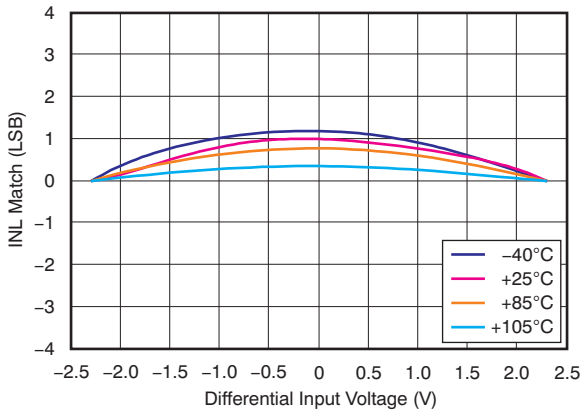


Figure 3.

INTEGRAL NONLINEARITY vs TEMPERATURE

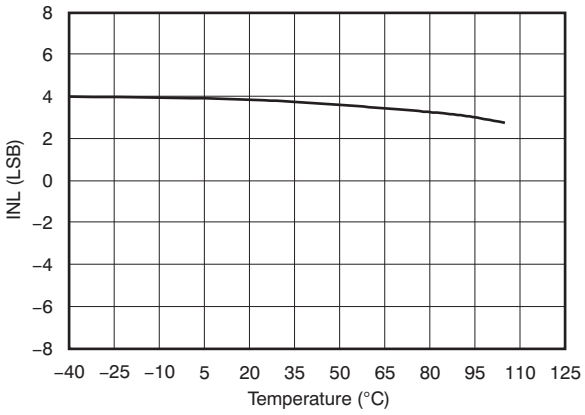


Figure 4.

OFFSET ERROR vs ANALOG SUPPLY VOLTAGE

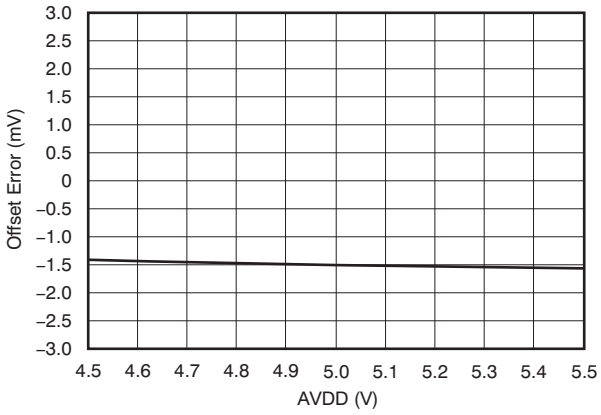


Figure 5.

OFFSET ERROR AND MATCH vs TEMPERATURE

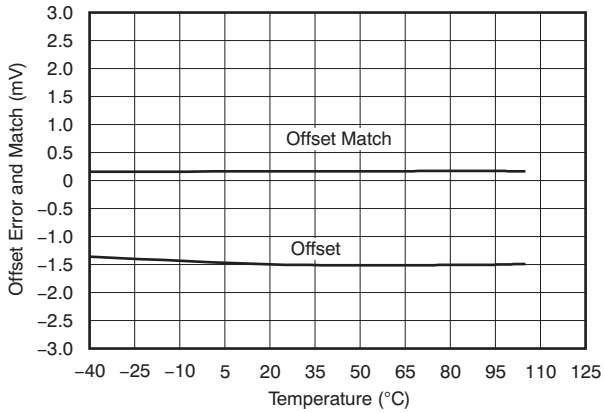


Figure 6.

GAIN ERROR AND MATCH vs TEMPERATURE

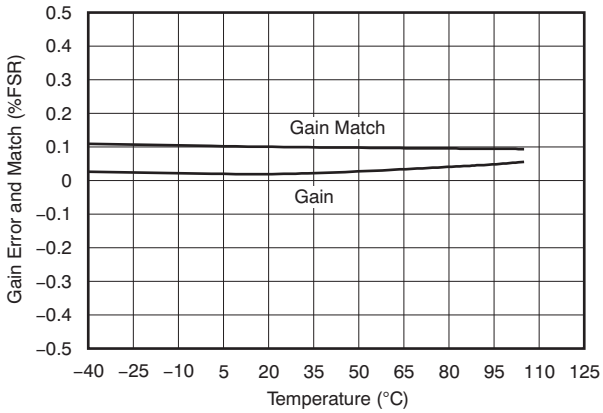


Figure 7.

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TYPICAL CHARACTERISTICS (continued)

At AVDD = 5V, BVDD = 3V, CHx+ = +0.2V to +4.8V, CHx– = +2.5V, V_{REFIN} = V_{REFOUT} = 2.5V (internal), CLKSEL = 1, and 16-bit Sinc^3 filter, with OSR = 256, unless otherwise noted.

POWER-SUPPLY REJECTION RATIO vs RIPPLE FREQUENCY

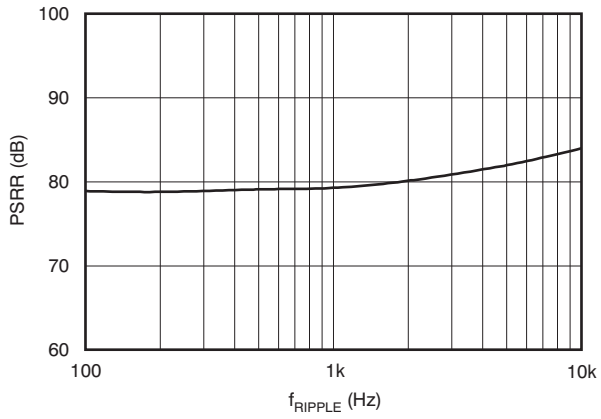


Figure 8.

COMMON-MODE REJECTION RATIO vs INPUT SIGNAL FREQUENCY

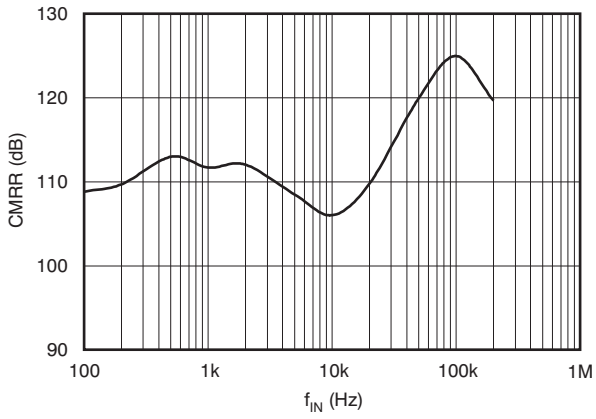


Figure 9.

INTERNAL CLOCK FREQUENCY ANALOG SUPPLY VOLTAGE

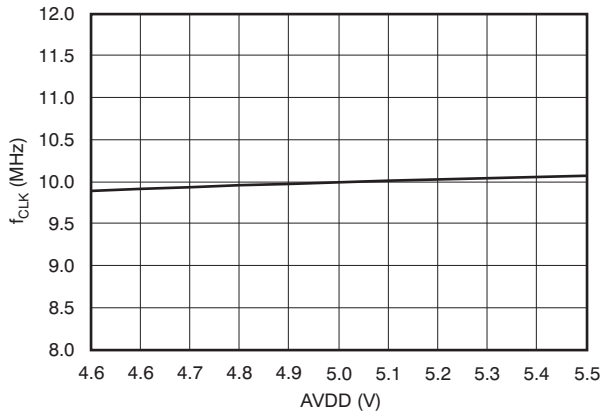


Figure 10.

INTERNAL CLOCK FREQUENCY vs TEMPERATURE

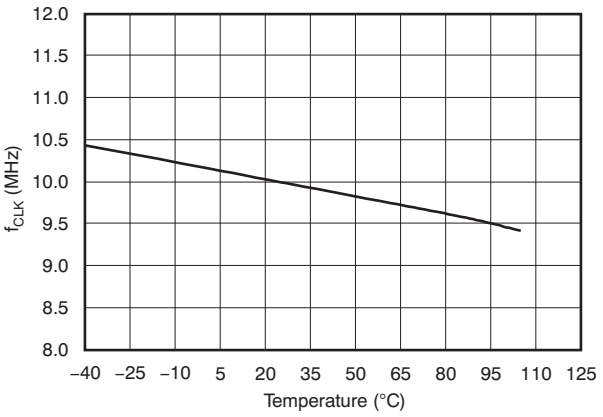


Figure 11.

TOTAL HARMONIC DISTORTION AND SPURIOUS-FREE DYNAMIC RANGE vs INPUT FREQUENCY

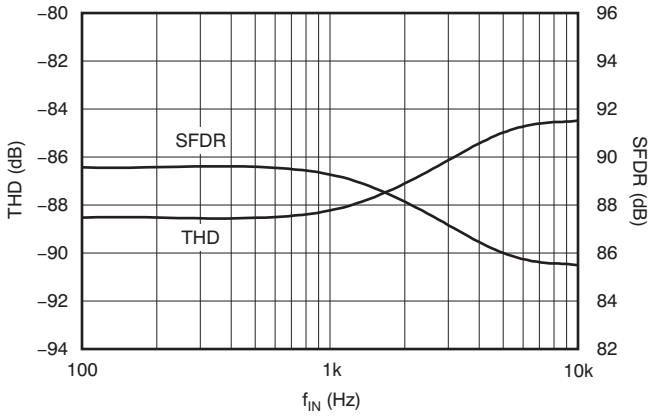


Figure 12.

TOTAL HARMONIC DISTORTION AND SPURIOUS-FREE DYNAMIC RANGE vs TEMPERATURE

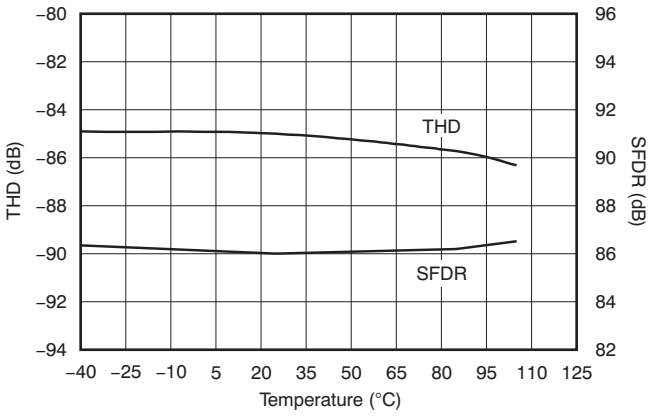


Figure 13.

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TYPICAL CHARACTERISTICS (continued)

At AVDD = 5V, BVDD = 3V, CHx+ = +0.2V to +4.8V, CHx– = +2.5V, V_{REFIN} = V_{REFOUT} = 2.5V (internal), CLKSEL = 1, and 16-bit Sinc^3 filter, with OSR = 256, unless otherwise noted.

SIGNAL-TO-NOISE RATIO AND SIGNAL-TO-NOISE + DISTORTION vs INPUT FREQUENCY

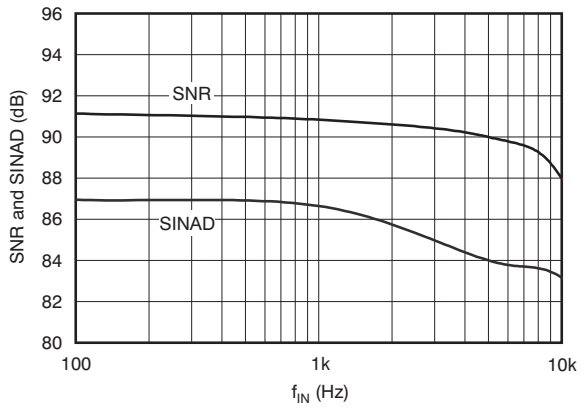


Figure 14.

SIGNAL-TO-NOISE RATIO AND SIGNAL-TO-NOISE + DISTORTION vs TEMPERATURE

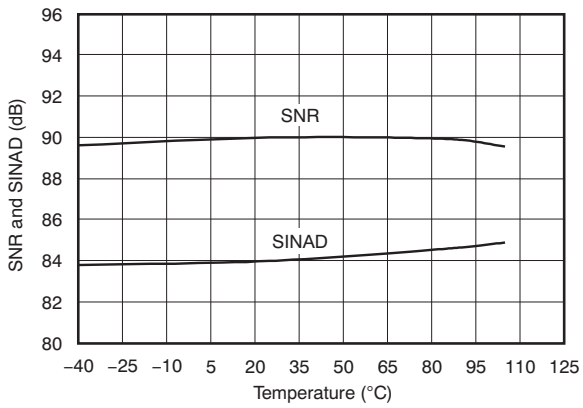


Figure 15.

FREQUENCY SPECTRUM (4096 Point FFT, f_{IN} = 1kHz, 4.6V_{PP})

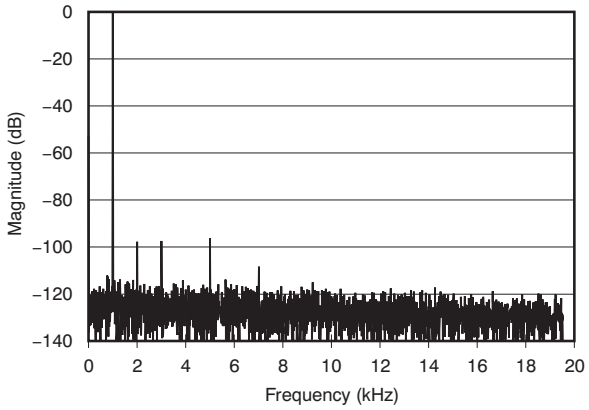


Figure 16.

FREQUENCY SPECTRUM (4096 Point FFT, f_{IN} = 5kHz, 4.6V_{PP})

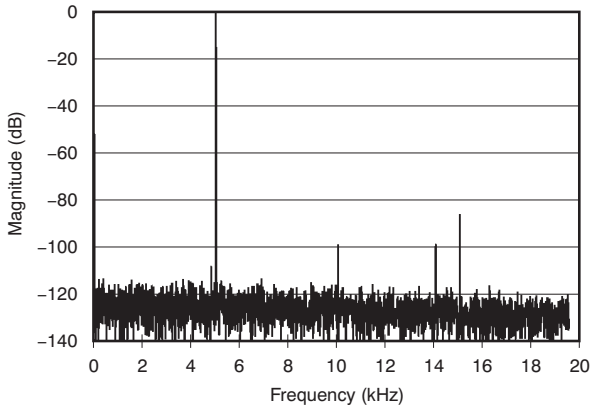


Figure 17.

INTERNAL REFERENCE VOLTAGE vs TEMPERATURE

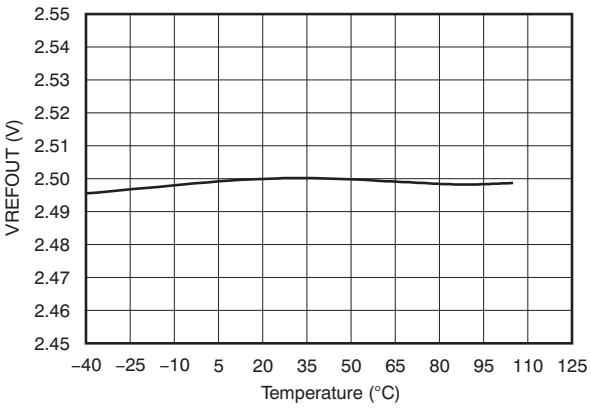


Figure 18.

SUPPLY CURRENT vs TEMPERATURE

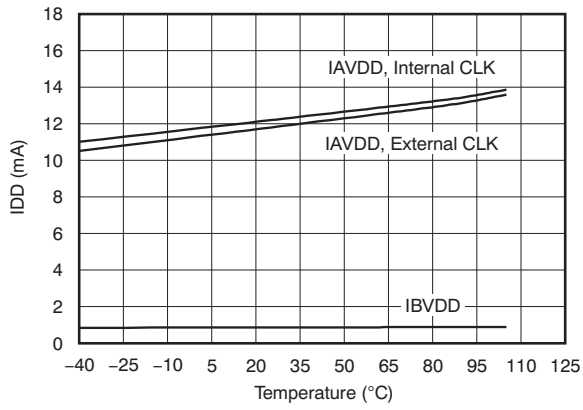


Figure 19.

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GENERAL DESCRIPTION

The ADS1209 is a two-channel, second-order, CMOS device with two delta-sigma (ΔΣ) modulators, designed for medium- to high-resolution A/D signal conversions from dc to 40kHz (filter response –3dB) if an oversampling ratio (OSR) of 64 is chosen. The output of the converter (OUTx) provides a stream of digital ones and zeros. The time average of this serial output is proportional to the analog input voltage.

The modulator shifts the quantization noise to high frequencies. A low-pass digital filter should be used at the output of the ΔΣ modulator. The filter serves two functions. First, it filters out high-frequency noise. Second, the filter converts the 1-bit data stream at a high sampling rate into a higher-bit data word at a lower rate (decimation).

An application-specific integrated circuit (ASIC) or field-programmable gate array (FPGA) can be used to implement the digital filter. Alternatively, TI's AMC1210 offers four programmable digital filters that can be used. Figure 20 and Figure 21 show typical application circuits with the ADS1209 connected to an FPGA or ASIC.

The overall performance (that is, speed and accuracy) depends on the selection of an appropriate OSR and filter type. A higher OSR produces greater output accuracy while operating at a lower data rate. Alternatively, a lower OSR produces lower output accuracy, but operates at a higher data rate. This system allows flexibility with the digital filter design and is capable of A/D conversion results that have a dynamic range exceeding 86dB with an OSR = 256.

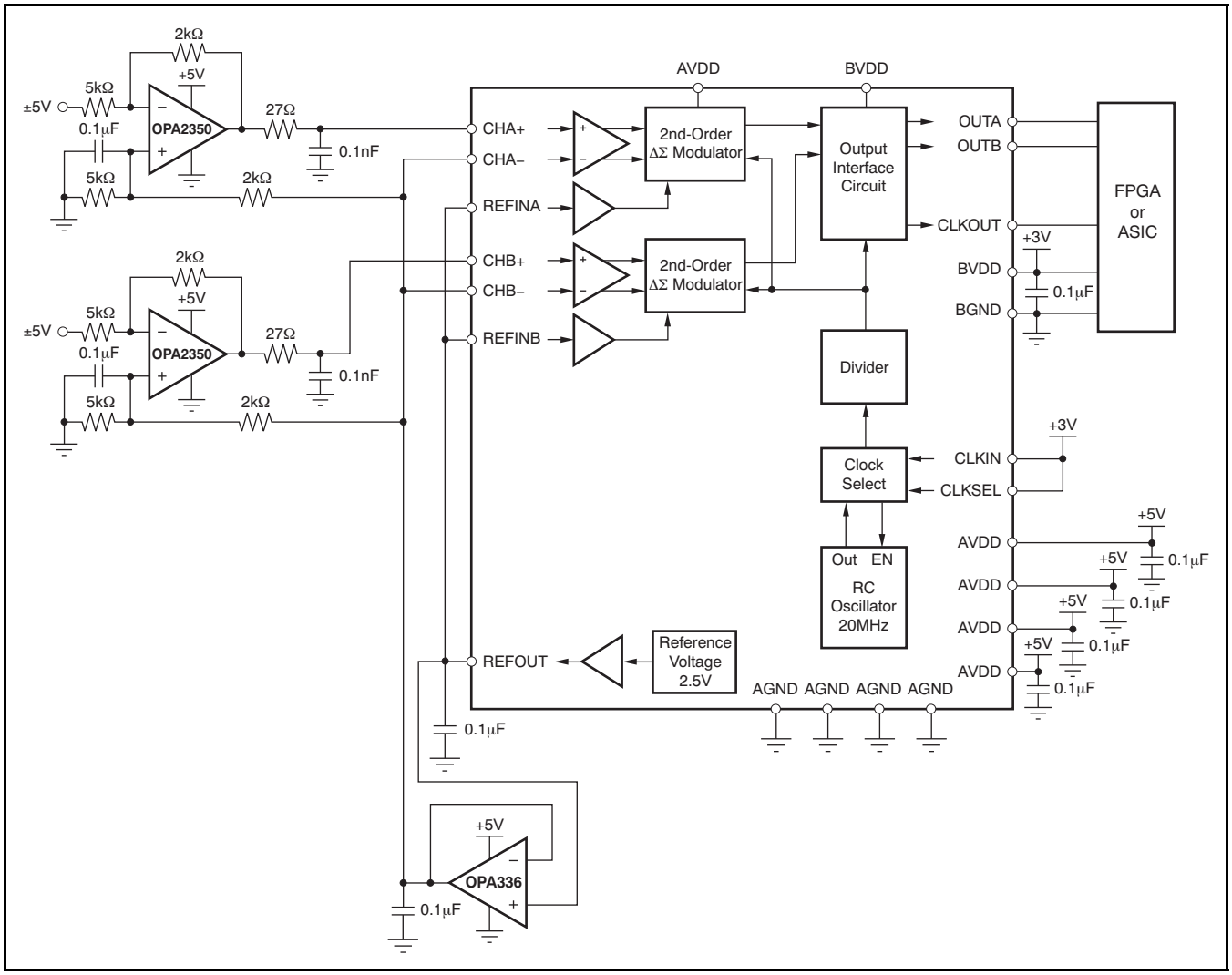


Figure 20. Single-Ended Connection Diagram for the ADS1209 ΔΣ Modulator

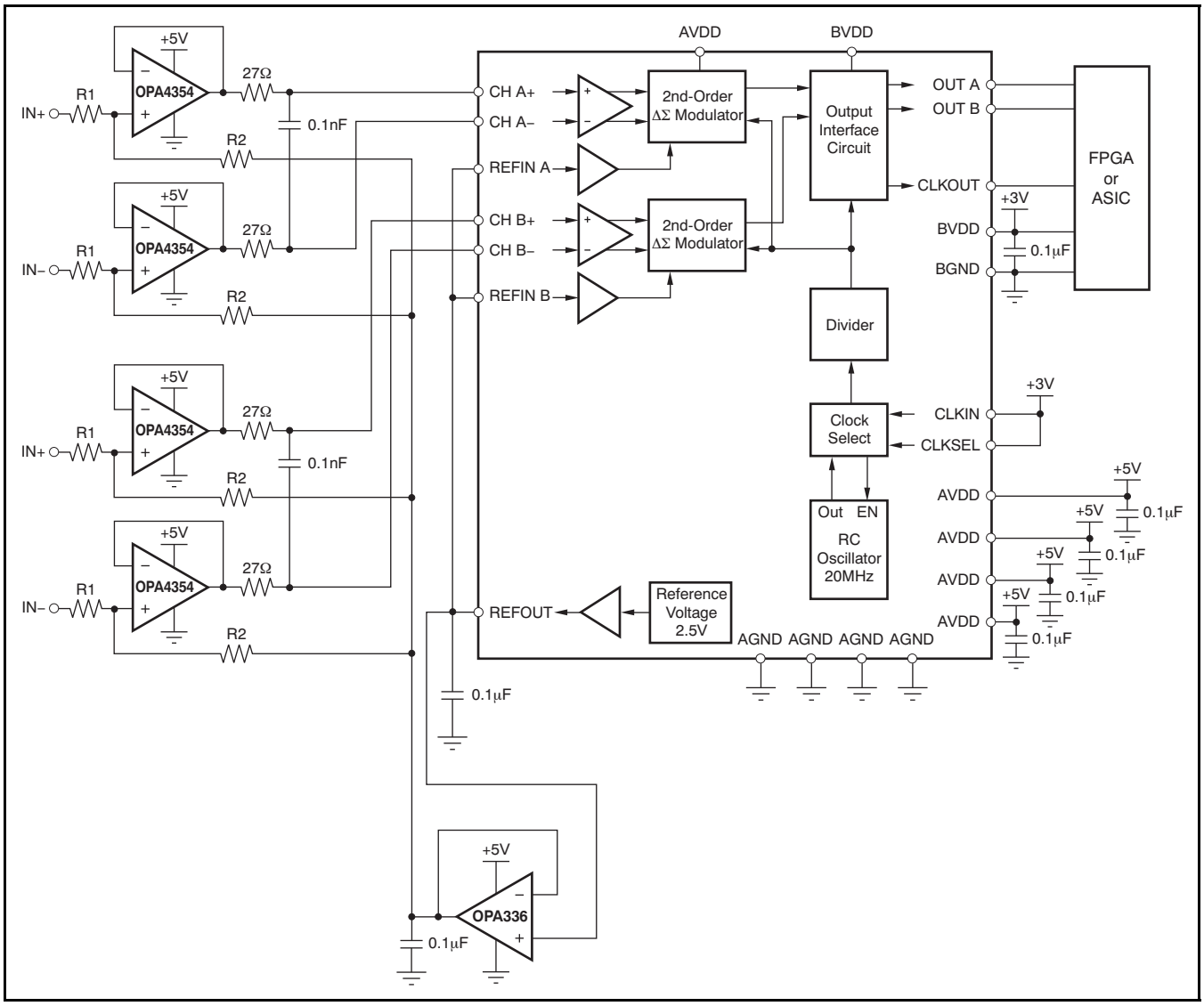


Figure 21. Differential Connection Diagram for the ADS1209 ΔΣ Modulator

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THEORY OF OPERATION

The differential analog input of the ADS1209 is implemented with a switched-capacitor circuit. This circuit implements a second-order modulator stage, which digitizes the analog input signal into a 1-bit output stream. The clock source can be internal as well as external. Every analog input signal is continuously sampled by the modulator and compared to a reference voltage that is applied to the REFINx pin. A digital stream that represents the analog input voltage over time appears at the output of the corresponding converter.

ANALOG INPUT STAGE

Analog Input

The topology of the analog inputs of ADS1209 is based on fully differential switched-capacitor architecture. This input stage provides the mechanism to achieve low system noise, high common-mode rejection, and excellent power-supply rejection.

The input impedance of the analog input depends on the modulator clock frequency (f_{MOD}). Figure 22 shows the basic input structure of one channel of the ADS1209. The relationship between the input impedance of the ADS1209 and the modulator clock frequency is:

$$Z_{IN} = \frac{100k\Omega}{f_{MOD}/10MHz} \quad (1)$$

The input impedance becomes a consideration in designs where the source impedance of the input signal is high. This high impedance may cause degradation in gain, linearity, and THD. The importance of this effect depends on the desired system performance. There are two restrictions on the analog input signals, CHx+ and CHx–. If the input voltage exceeds the range (AGND – 0.3V) to (AVDD + 0.3V), the input current must be limited to 10mA because the input protection diodes on the front end of the converter begin to turn on. In addition, the linearity and noise performance of the device meet the stored specifications only when the differential analog voltage resides within ±2.3V (with V_{REFIN} as a midpoint); however, the FSR input voltage is ±2.5V.

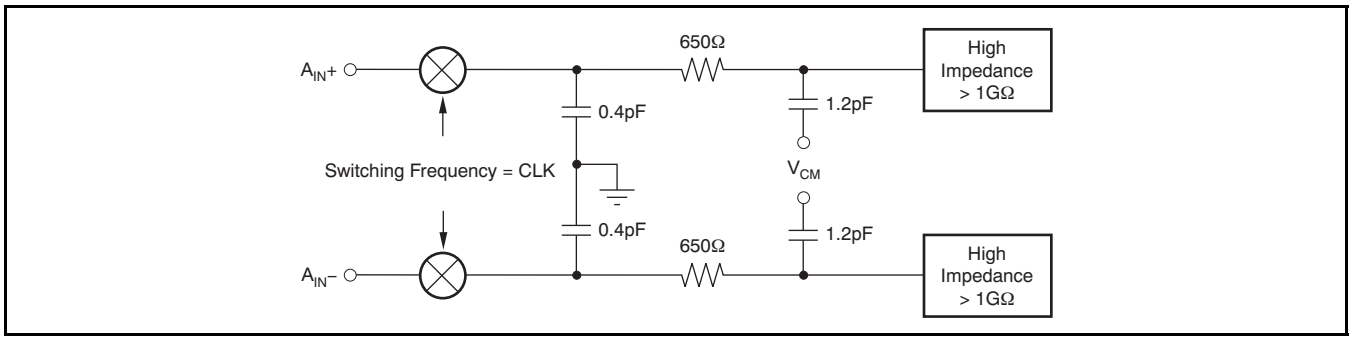


Figure 22. Input Impedance of the ADS1209

Modulator

The ADS1209 can be operated in two modes. When CKLSEL = 1, the two modulators operate using the internal clock, which is fixed at 20MHz. When CKLSEL = 0, the modulators operate using an external clock. In both modes, the clock is internally divided by two and functions as the modulator clock. The frequency of the external clock can vary from 1MHz to 24MHz to adjust for the clock requirements of the application.

The modulator topology is a second-order, switched-capacitor, ΔΣ modulator, such as the one conceptualized in Figure 23. The analog input voltage and the output of the 1-bit digital-to-analog converter (DAC) are differentiated, providing analog voltages at X_2 and X_3. The voltages at X_2 and X_3 are presented to the respective individual integrators. The output of these integrators progresses in a negative or positive direction. When the value of the signal at X_4 equals the comparator reference voltage, the output of the comparator switches from low to high, or vice versa, depending on its original state. When the output value of the comparator switches direction, the 1-bit DAC responds on the next clock pulse by changing its analog output voltage at X_6, causing the integrators to progress in the opposite direction. The feedback of the modulator to the front end of the integrators forces the value of the integrator output to track the average of the input.

DIGITAL OUTPUT

A differential input signal of 0V ideally produces a stream of ones and zeros that are high 50% of the time and low 50% of the time. A differential input of +2.3V produces a stream of ones and zeros that are high 92% of the time. A differential input of –2.3V produces a stream of ones and zeros that are high 8% of the time. The input voltage versus the output modulator signal is shown in Figure 24.

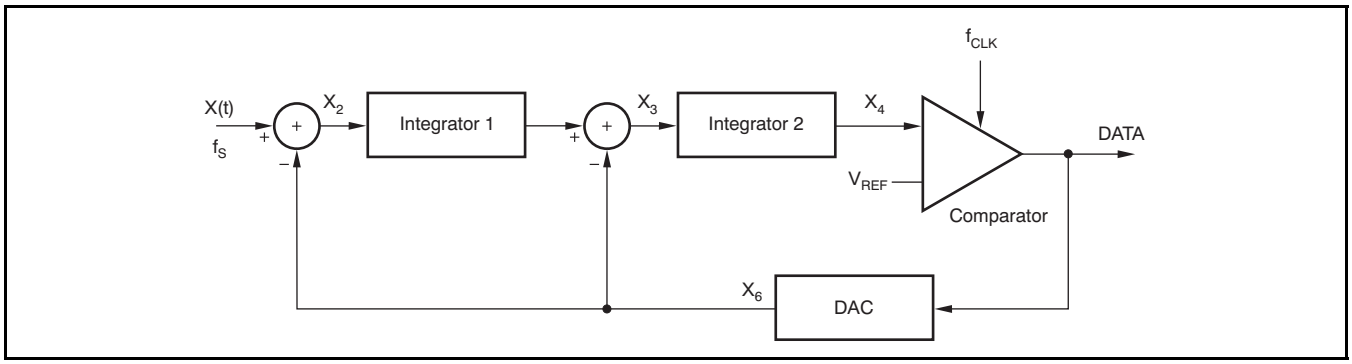


Figure 23. Block Diagram of the Second-Order Modulator

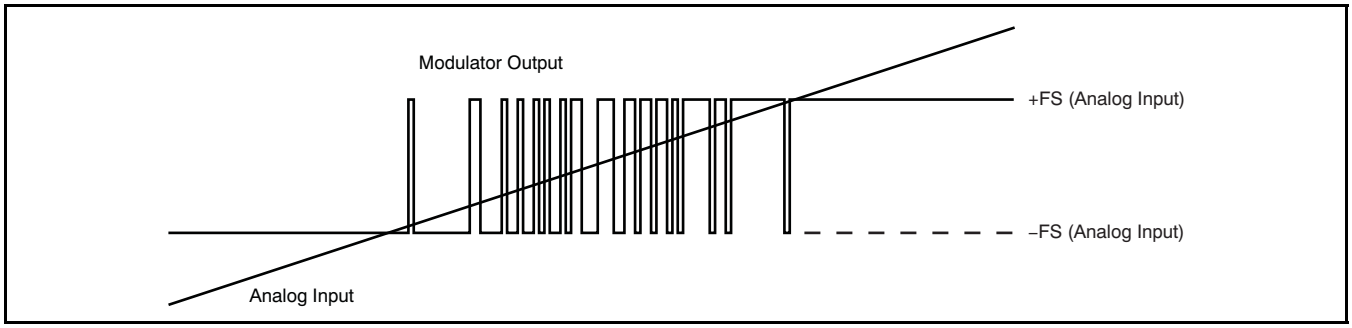


Figure 24. Analog Input vs Modulator Output of the ADS1209

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DIGITAL INTERFACE

INTRODUCTION

The analog signal connected to the input of the ΔΣ modulator is converted using the clock signal applied to the modulator. The result of the conversion (or modulation) is available on one of the OUTx pins, depending on the modulator. In addition, a common clock output signal (CLKOUT) for both simultaneously-sampling modulators is provided. If CLKSEL = 1, CLKIN must not be left floating, but should tied to BVDD or BGND.

MODES OF OPERATION

The device clock of the ADS1209 is 20MHz by default. The device clock can either be generated by the internal 20MHz RC oscillator or can be provided by an external clock source. For this purpose, the CLKIN pin is provided; it is controlled by the mode setting, CLKSEL.

The device clock is divided by two before being used as the modulator clock. Therefore, the default clock frequency of the modulator is 10MHz. With a possible external clock range of 1MHz to 24MHz, the modulator operates between 500kHz and 12MHz.

FILTER USAGE

The modulator generates a bitstream. In order to output a digital word equivalent to the analog input voltage, the bitstream must be processed by a digital filter.

A simple filter, built with minimal effort and hardware, is the Sinc^3 filter shown in Equation 2:

$$H(z) = \left(\frac{1 - z^{-OSR}}{1 - z^{-1}} \right)^3 \quad (2)$$

This filter provides the best output performance with a relatively low number of gates required for implementation. For oversampling ratios in the range of 16 to 256, this filter architecture represents a good choice. All the characterizations in this data sheet are done using a Sinc^3 filter with an oversampling ratio of OSR = 256 and an output word width of 16 bits.

In a Sinc^3 filter response (shown in Figure 25 and Figure 26), the location of the first notch occurs at the frequency of output data rate $f_{DATA} = f_{MOD}/OSR$. The –3dB point is located at half the Nyquist frequency or $f_{DATA}/4$.

This behavior can be adjusted by a cascaded filter structure. For example, the first decimation stage can be a Sinc^3 filter with a low OSR, and the second stage a high-order filter.

For more information, see application note SBAA094, *Combining the ADS1202 with an FPGA Digital Filter for Current Measurement in Motor Control Applications*, available for download at www.ti.com.

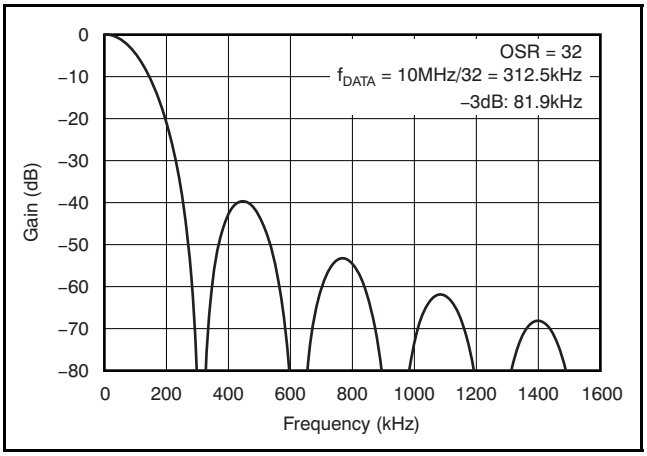


Figure 25. Frequency Response of Sinc^3 Filter (OSR = 32)

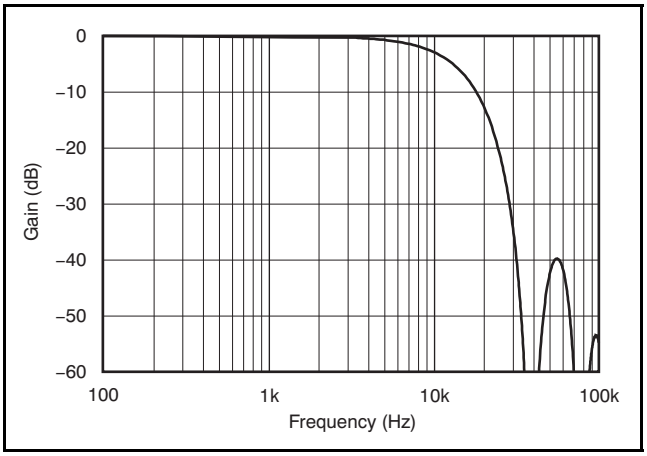


Figure 26. Frequency Response of Sinc^3 Filter (OSR = 256)

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The effective number of bits (ENOB) can be used to compare the performance of A/D converters and ΔΣ modulators. Figure 27 shows the ENOB of the ADS1209 with different filter types. In this data sheet, the ENOB is calculated from the SNR as shown in Equation 3:

$$SNR = 1.76dB + 6.02dB \times ENOB \quad (3)$$

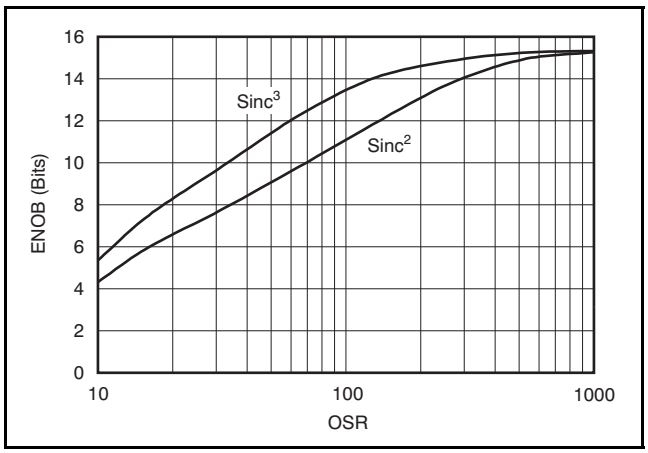


Figure 27. Measured ENOB vs OSR

In motor-control applications, a very fast response time is required for overcurrent detection. There is a constraint between 1μs and 5μs with 3 bits to 7 bits of resolution. The time for full settling depends on the filter order. Therefore, the full settling of the $Sinc^3$ filter requires three data clocks and the $Sinc^2$ filter requires two data clocks. The data clock is equal to the modulator clock divided by the OSR. For overcurrent protection, filter types other than $Sinc^3$ may be a better choice. A simple example is a $Sinc^2$ filter. The Sincfast is a modified $Sinc^2$ filter as Equation 4 shows:

$$H(z) = \left[\frac{1 - z^{-OSR}}{1 - z^{-1}}\right]^2 (1 + z^{-2 \times OSR}) \quad (4)$$

Figure 28 compares the settling time of different filter types operating with a 10MHz modulator clock.

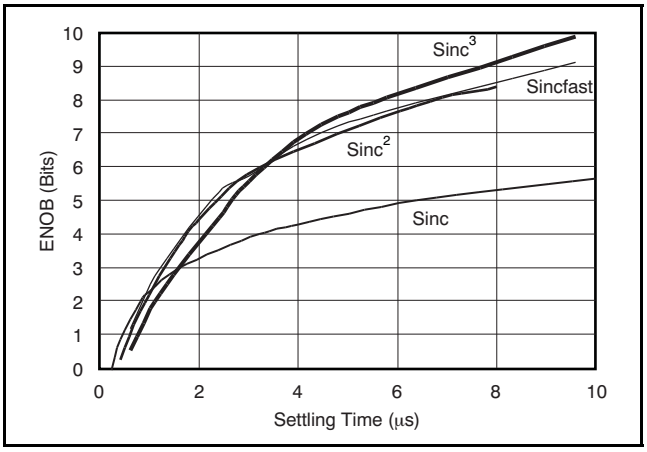


Figure 28. Measured ENOB vs Settling Time

For more information, see application note SBAA094, *Combining the ADS1202 with an FPGA Digital Filter for Current Measurement in Motor Control Applications*, available for download at www.ti.com.

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LAYOUT CONSIDERATIONS

POWER SUPPLIES

An applied external digital filter rejects high-frequency noise. PSRR and CMRR improve at higher frequencies because the digital filter suppresses high-frequency noise. However, the suppression of the filter is not infinite while high-frequency noise continues to influence the conversion result.

Inputs to the ADS1209, such as CHx+, CHx–, and CLKIN, should not be present before the power supply is on. Violating this condition could cause latch-up. If these signals are present before the supply is on, series resistors should be used to limit the input current to a maximum of 10mA.

GROUNDING

Analog and digital sections of the design must be carefully and cleanly partitioned. Each section should have its own ground plane with a connection between them underneath the converter.

For multiple converters, connect the two ground planes as close as possible to each of the converters.

DECOUPLING

Good decoupling practices must be used for the ADS1209 and for all components in the design. All decoupling capacitors, specifically the 0.1μF ceramic capacitors, must be placed as close as possible to the pin being decoupled. A 1μF and 10μF capacitor, in parallel with the 0.1μF ceramic capacitor, can be used to decouple AVDD to AGND as well as BVDD to BGND. At least one 0.1μF ceramic capacitor must be used to decouple every AVDD to AGND and BVDD to BGND, as well as for the digital supply on each digital component.

The digital supply sets the I/O voltage for the interface and can be set within a range of 2.7V to 5.5V.

In cases where both the analog and digital I/O supplies share the same supply source, an RC filter of 10Ω and 0.1μF can be used to help reduce the noise in the analog supply.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ADS1209SPW	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ADS1209
ADS1209SPW.B	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ADS1209
ADS1209SPWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ADS1209
ADS1209SPWR.B	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ADS1209

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

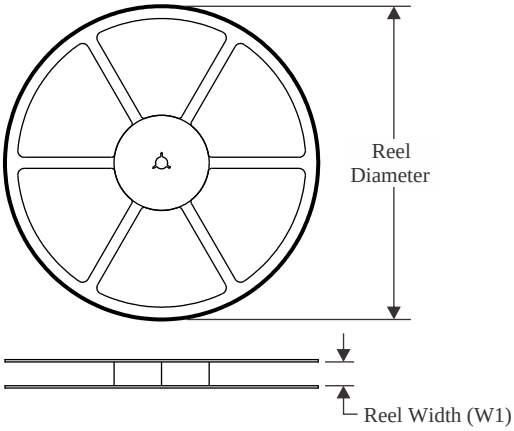
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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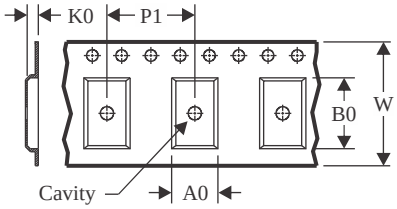
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REEL DIMENSIONS

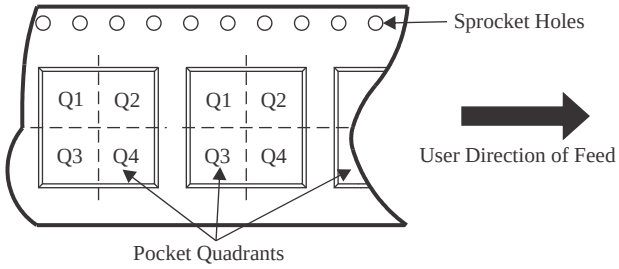


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

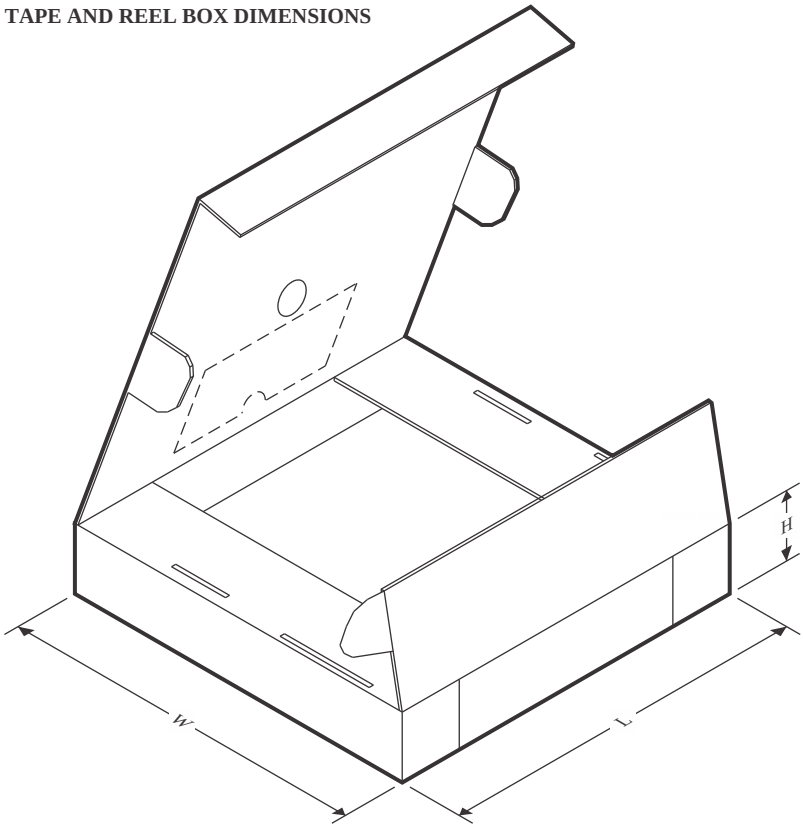
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS1209SPWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

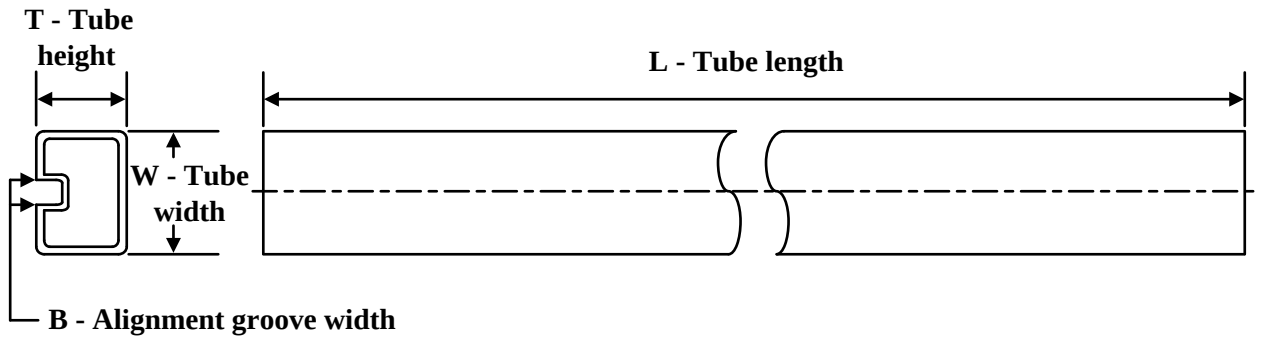
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS1209SPWR	TSSOP	PW	24	2000	350.0	350.0	43.0

TUBE



*All dimensions are nominal

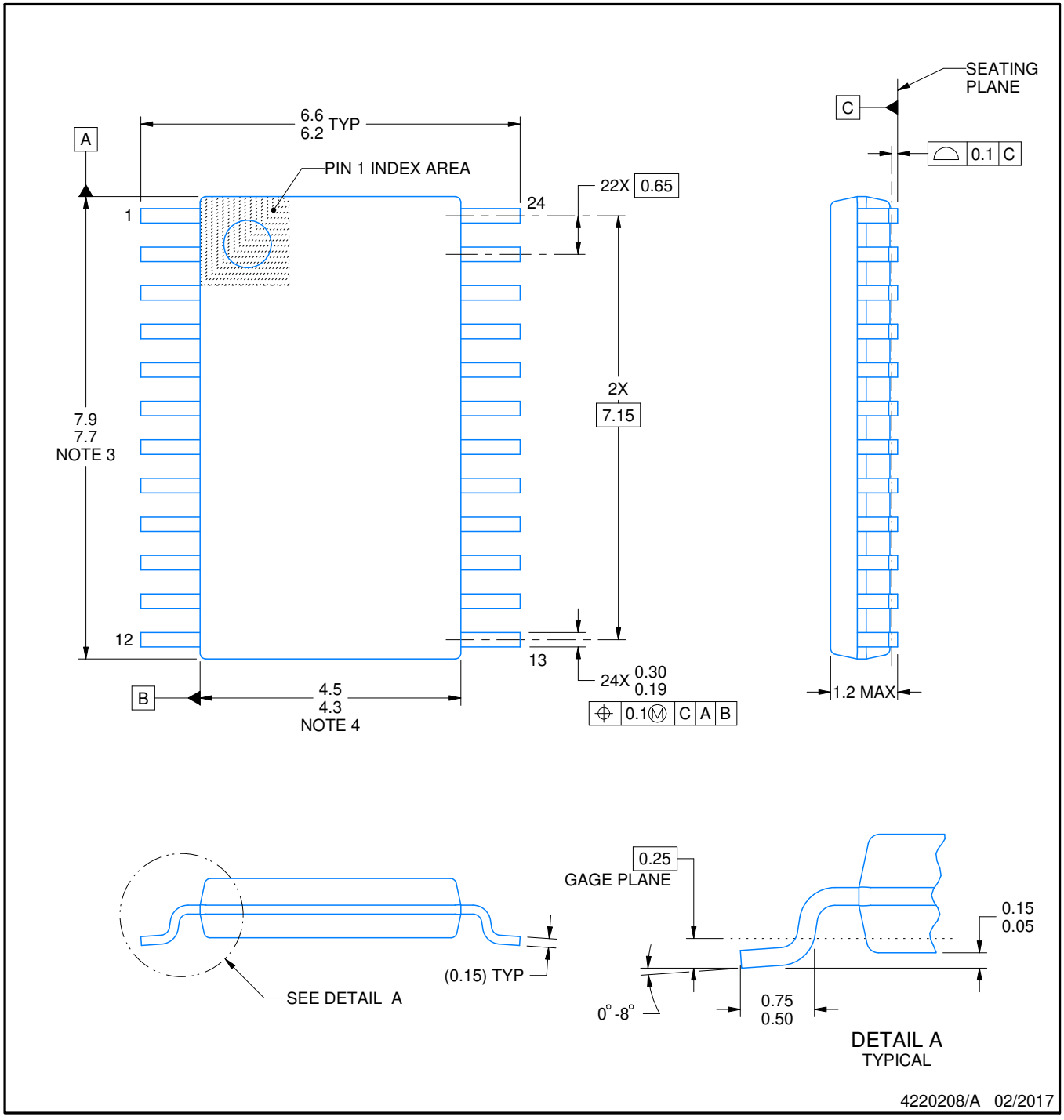
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ADS1209SPW	PW	TSSOP	24	60	530	10.2	3600	3.5
ADS1209SPW.B	PW	TSSOP	24	60	530	10.2	3600	3.5

PACKAGE OUTLINE

PW0024A

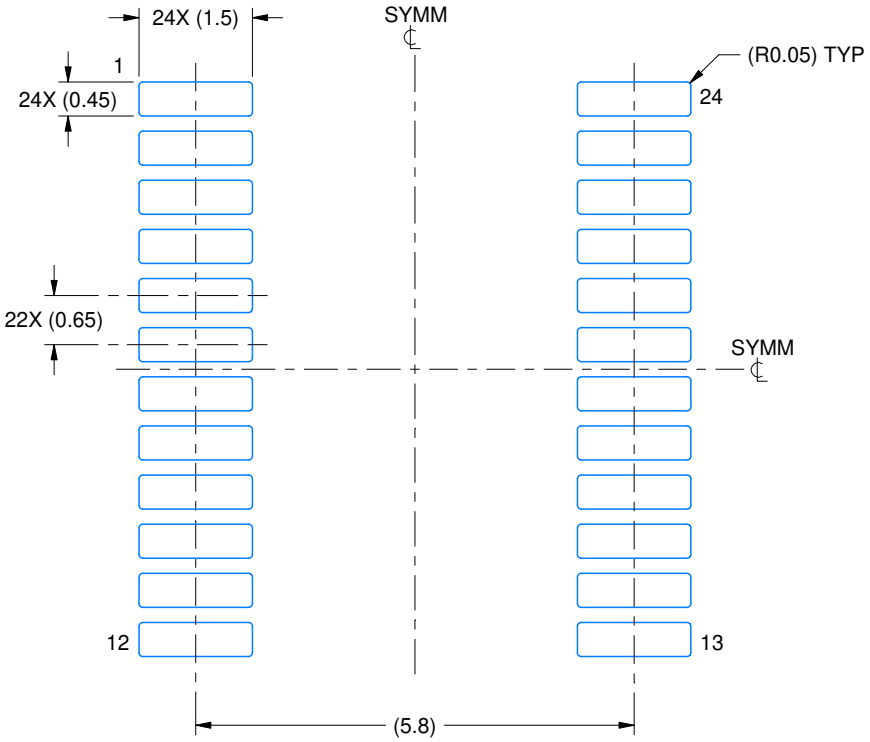
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

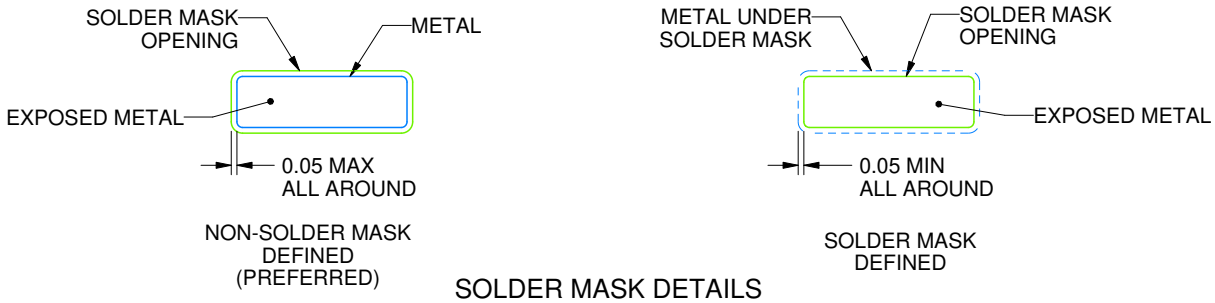


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

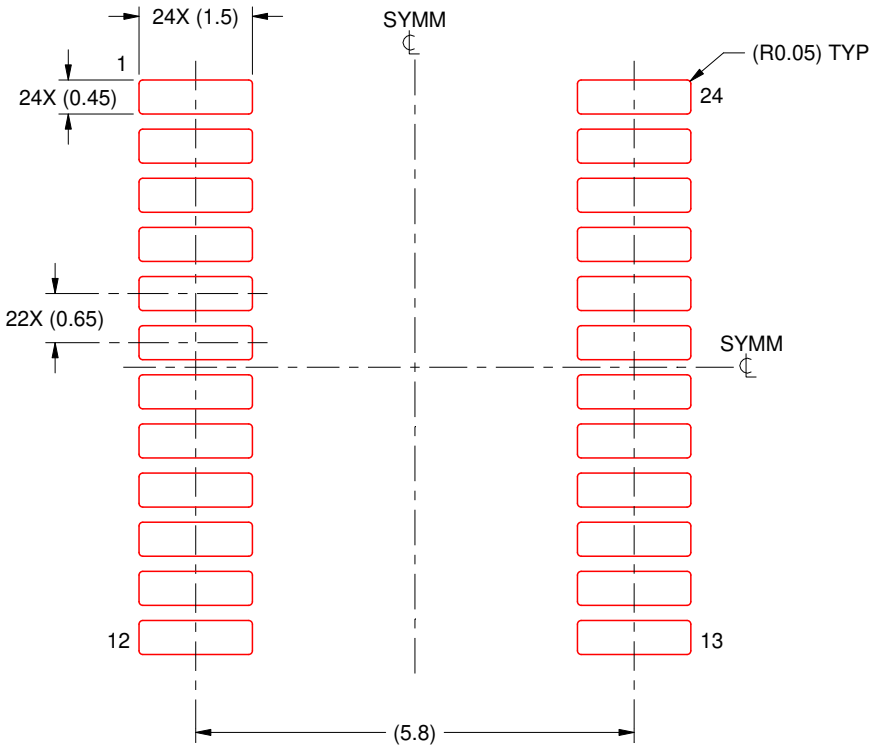


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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Last updated 10/2025